

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S85	104	S60 S66 S74 S78 S83	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S84	546176	die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S83	16	S81 and S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S82	2264	S75 with S72	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S81	129	S80 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S80	159	S72 near S79	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S79	1695793	((multi\$4 multiplici\$3 plural\$4 dual) adj (layer film) multilayer\$3 sublayer\$3 (multi sub) adj layer\$3 layered laminat\$4 stack\$4 Tripart\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S78	33	S77 and S71	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S77	33	S76 and S69	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S76	33	S73 and S75	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19

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S75	1865708	adhe\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S74	26	S73 and S67	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S73	52	S71 adj S72	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S72	26322	(bond ball bump) adj (pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S71	3315798	S70 S68	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S70	2514329	(polymer\$6 polyimid\$4 co adj polyme\$4 copolyme\$4 copolyimid\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S69	23172	(bond) adj (pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S68	1066934	silicon polysilicon non adj metal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S67	2111394	test\$4 inspect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S66	40	S65 not S62	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19

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S65	56	S64 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S64	417	S63 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S63	470	S53 with S54 with S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S62	16	S59 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S61	58834	(contact\$4 bond) adj (pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S60	6	"6,022,750".pn. "20030106209" "20010048980"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S59	180	S57 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S58	30867824	(@ad @pd) <"20030722"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S57	201	S56 near6 S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S56	4383	S53 near4 S54	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19

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S55	1397893	density real adj estate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S54	2327037	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S52	59	S50 and S51	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:19
S86	72	S84 and S85	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:24
S89	1390	(257/48).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/17 19:26
S88	3645	(257/758).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/17 19:26
S90	34	S88 and S89	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:41
S91	2343582	si silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:42
S92	18	S90 and S91	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:43
S93	3216858	insulat\$4 dielectric passivation sio sin oxide nitride ild imd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:46

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S95	8857012	surface contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:47
S94	468017	S91 with S93	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:47
S53	13986	((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/17 19:49
S87	5001	(257/48,758).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/18 08:21
L1	5001	(257/48,758).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/18 08:21
S96	152697	S94 with S95	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:22
L6	152697	L4 with L5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:22
L5	8857012	surface contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:22
L4	468017	L2 with L3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:22
L3	3216858	insulat\$4 dielectric passivation sio sin oxide nitride ild imd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:22

EAST Search History

L2	2343582	si silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:22
S5	2159102	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:23
S4	12943	((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:23
L7	13986	((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:23
L11	1285	10 and 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:24
L10	1330	9 and 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:24
L9	3237	1 and 2 and 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:24
L8	2327037	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:24
L13	2832647	(test\$4 repair\$4 edit\$4 analyz\$4 evaluat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:30
L12	271	11 and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:30

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L15	6450	fib	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:34
L14	420	11 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:34
L16	3	14 and 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/18 08:36

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L17	54990	2.clm.	US-PGPUB	OR	ON	2006/03/18 08:39
L19	130866	3.clm.	US-PGPUB	OR	ON	2006/03/18 08:40
L18	238888	bond pad	US-PGPUB	OR	ON	2006/03/18 08:40
L23	55708	18.clm.	US-PGPUB	OR	ON	2006/03/18 08:41
L22	303	7.clm.	US-PGPUB	OR	ON	2006/03/18 08:41
L21	85670	8.clm.	US-PGPUB	OR	ON	2006/03/18 08:41
L20	382164	5.clm.	US-PGPUB	OR	ON	2006/03/18 08:41
L27	17	24 and 26	US-PGPUB	OR	ON	2006/03/18 08:42
L26	79	19 same 20 same 22	US-PGPUB	OR	ON	2006/03/18 08:42
L25	50595	19 same 20	US-PGPUB	OR	ON	2006/03/18 08:42
L24	56	17 and 19 and 20 and 21 and 22 and 23	US-PGPUB	OR	ON	2006/03/18 08:42